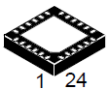
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

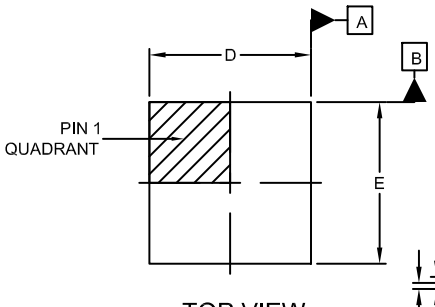


QFNW24 4x4, 0.5P
CASE 484AU
ISSUE O

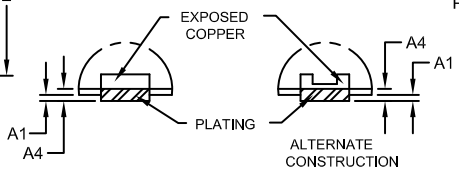
DATE 07 AUG 2020

NOTES:

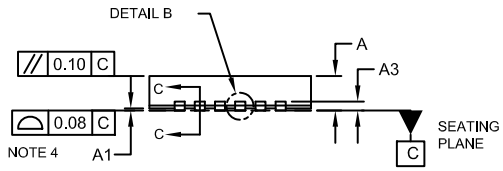
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



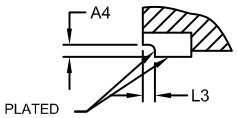
TOP VIEW



DETAIL B

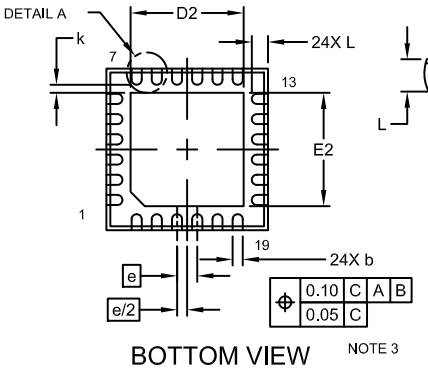


SIDE VIEW

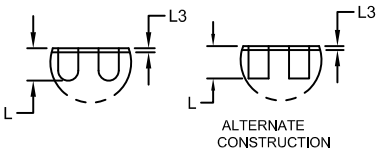


SECTION C-C

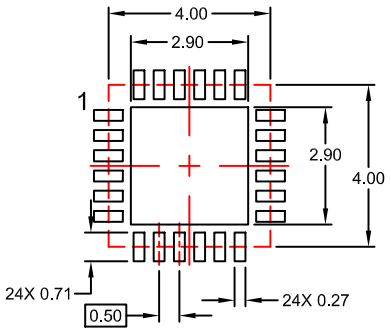
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	---	---	0.05
A3		0.20 REF	
A4	0.10	---	---
b	0.20	0.25	0.30
D	3.90	4.00	4.10
D2	2.70	2.80	2.90
E	3.90	4.00	4.10
E2	2.70	2.80	2.90
e		0.50 BSC	
k	0.20	---	---
L	0.35	0.40	0.45
L3		0.05 REF	



BOTTOM VIEW



DETAIL A



LAND PATTERN RECOMMENDATION*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**QFNW24 4x4, 0.5P**	**PAGE 1 OF 1**